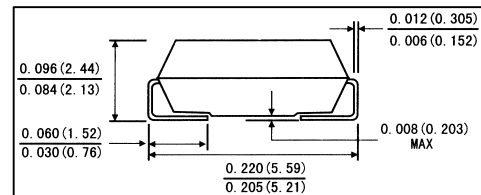
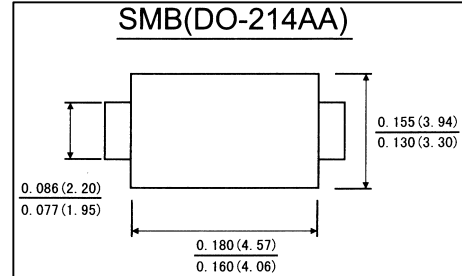


FEATURES

- . For surface mounted applications
- . Glass passivated junction
- . Low profile package
- . Built-in strain relief , ideal for automated placement
- . Plastic package has Underwrites Laboratory Flammability Classification 94V-0
- . High temperature soldering guaranteed: 250°C/10 seconds, at terminals

MECHANICAL DATA

- . **Case:** JEDEC SMA(DO-214AA) molded plastic
- . **Terminals:** Plated axial leads solderable per MIL-STD-750,method 2026
- . **Polarity:** Color band denotes cathode end
- . **Mounting Position:** Any
- . **Weight:** 0.003 ounce, 0.093 gram



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(Ratings at 25°C ambient temperature unless otherwise specified,Single phase,half wave 60Hz,resistive or inductive)

load. For capacitive load,derate current by 20%)

	Symbols	S2A	S2B	S2D	S2G	S2J	S2K	S2M	Units	
Maximum Recurrent peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	Volts	
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	Volts	
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	100	Volts	
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	1.5							Amp	
Peak forward surge current (8.3ms half sing wave superimposed on rated load (JEDEC method) $T_L=100^\circ\text{C}$	I_{FSM}	50.0							Amps	
Maximum instantaneous forward voltage at 1.0 A	V_F	1.15							Volts	
Maximum reverse recovery time(Note 1) current at rated DC Blocking Voltage	I_R	$T_A=25^\circ\text{C}$	1.0							μA
		$T_A=125^\circ\text{C}$	125							
Typical Thermal Resistance(Note 2)	$R_{\theta_{JL}}$	16.0							$^\circ\text{C/W}$	
	$R_{\theta_{JA}}$	53.0								
Typical reverse recovery time(Note 3)	T_{rr}	2.0							μS	
Typical junction capacitance(Note 1)		30.0							pF	
Operating and storage temperature range	$T_J T_{STG}$	-55 to +150							$^\circ\text{C}$	

Notes: 1.Measured at 1MHz and applied reverse voltage of 4.0V DC.

2.Thermal resistance from junction to ambient and from junction to lead mounted on 0.2 X 0.2"(5.0 X 5.0mm)

copper pad areas. 3.Reverse recovery test conditions: $I_F=0.5A, I_R=1.0A, I_{rr}=0.25A$.

RATINGS AND CHARACTERISTIC CURVES S2A THRU S2M

FIG.1-FORWARD CURRENT DERATING CURVE

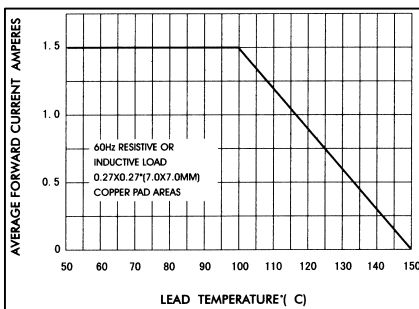


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

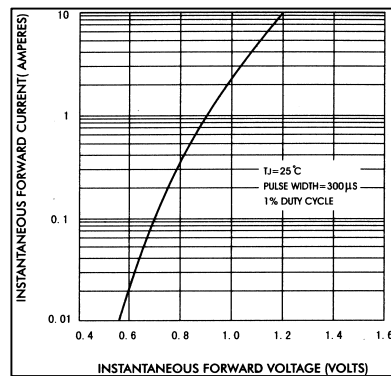


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

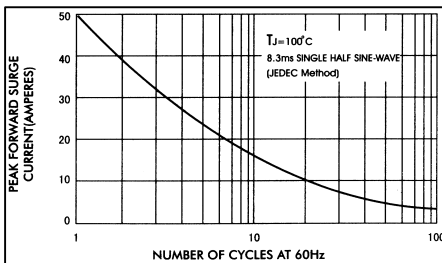


FIG.4-TYPICAL REVERSE CHARACTERISTICS

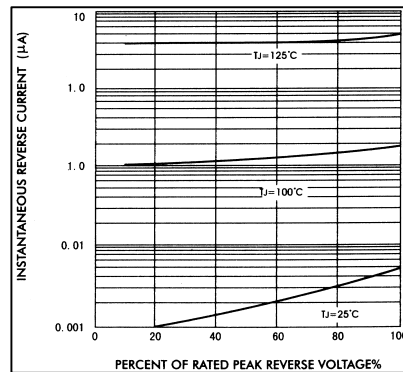


FIG.5-TYPICAL JUNCTION CAPACITANCE

